

# LNJ447W84RA1

## High Bright Surface Mounting Chip LED

1005 Type

### Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                     | Symbol    | Rating      | Unit             |
|-------------------------------|-----------|-------------|------------------|
| Power dissipation             | $P_D$     | 55          | mW               |
| Forward current               | $I_F$     | 20          | mA               |
| Pulse forward current *       | $I_{FP}$  | 60          | mA               |
| Reverse voltage               | $V_R$     | 4           | V                |
| Operating ambient temperature | $T_{opr}$ | -30 to +85  | $^\circ\text{C}$ |
| Storage temperature           | $T_{stg}$ | -40 to +100 | $^\circ\text{C}$ |

### Lighting Color

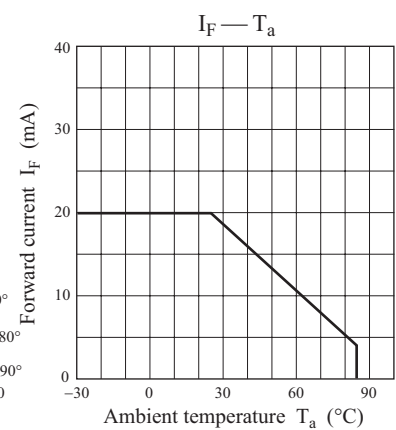
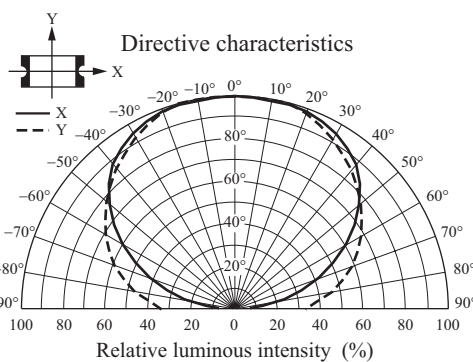
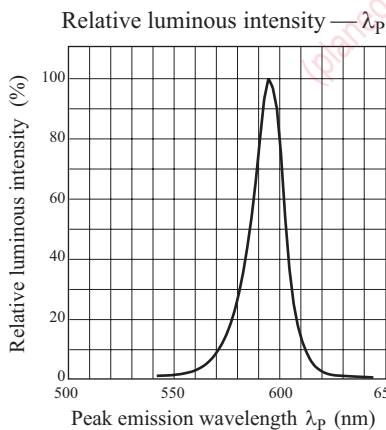
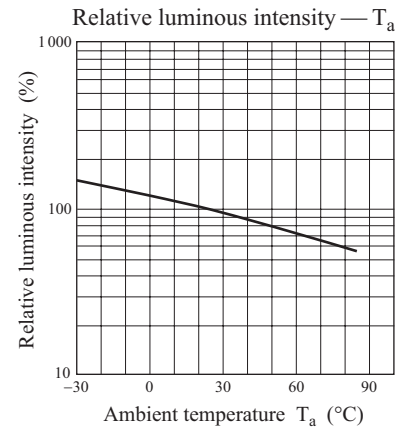
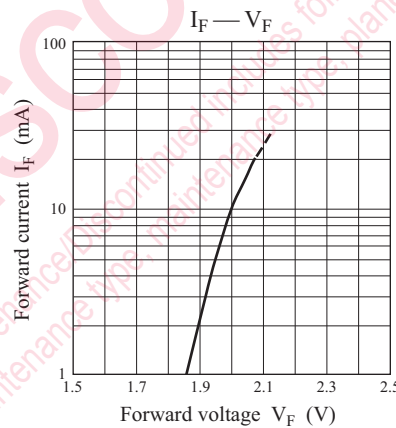
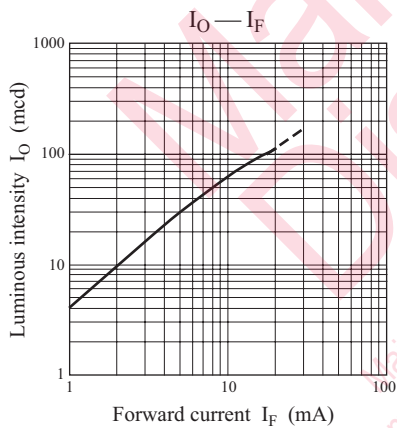
- Amber

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

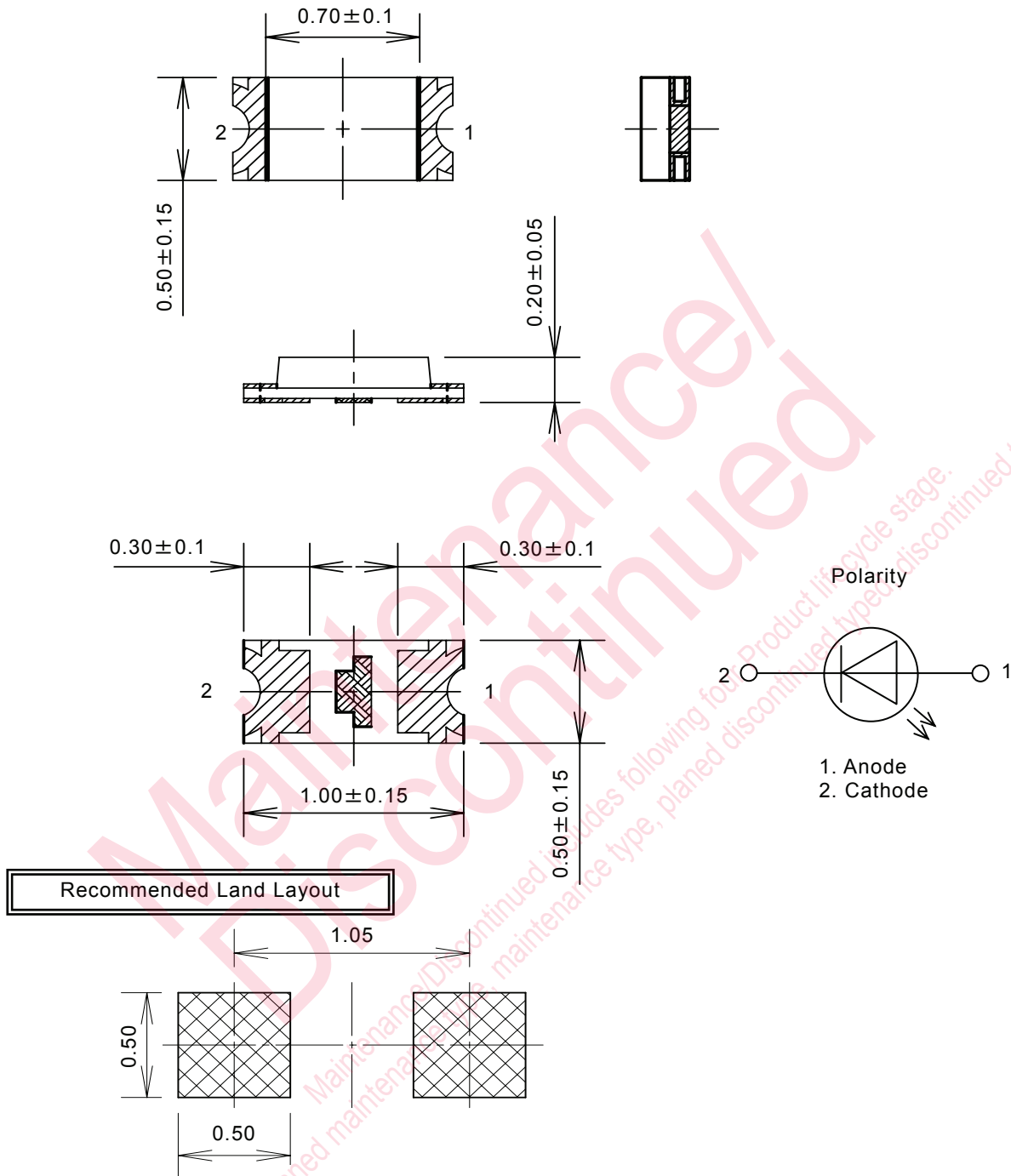
### Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter                       | Symbol          | Conditions           | Min  | Typ  | Max  | Unit          |
|---------------------------------|-----------------|----------------------|------|------|------|---------------|
| Luminous intensity *1           | $I_O$           | $I_F = 5 \text{ mA}$ | 19.5 | 30.0 | 52.4 | mcd           |
| Reverse current                 | $I_R$           | $V_R = 4 \text{ V}$  |      |      | 100  | $\mu\text{A}$ |
| Forward voltage                 | $V_F$           | $I_F = 5 \text{ mA}$ |      | 1.95 | 2.30 | V             |
| Peak emission wavelength        | $\lambda_p$     | $I_F = 5 \text{ mA}$ |      | 595  |      | nm            |
| Dominant emission wavelength *2 | $\lambda_d$     | $I_F = 5 \text{ mA}$ | 587  | 590  | 597  | nm            |
| Spectral half band width        | $\Delta\lambda$ | $I_F = 5 \text{ mA}$ |      | 15   |      | nm            |

Note) \*1: Measurement tolerance:  $\pm 20\%$   
 \*2: Measurement tolerance:  $\pm 2 \text{ nm}$



■ Package (Unit: mm)



(Note1) Electrode projection is not included in the package dimensions.

(Note2) About solder thickness, please examine the products yourself completely.

(Recommended thickness :  $t=0.10$  mm ~  $0.15$  mm)

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